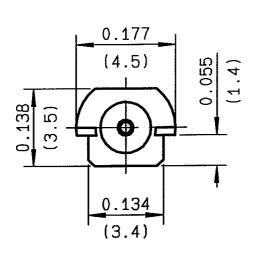
R110.422.100

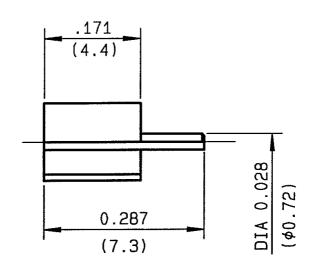
Series : MMCX



## Australian Representatives ROJONE, PTY LTD.

Tel: 02 9829 1555 E: sales@rojone.com.au www.rojone.com.au





All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER - PTFE	GOLD OVER NICKEL GOLD OVER NICKEL

Issue: 0422 A

In the effort to improve our products, we reserve the right to make changes judged to be



R110.422.100

Series : MMCX

**PACKAGING** 

Standard	Unit	Other
100	'W' option	Contact us

#### **SPECIFICATION**

#### **ELECTRICAL CHARACTERISTICS**

Impedance 50  $\Omega$ 

VSWR  $AD + 0.000 \times F(GHz) Maxi$ Insertion loss  $AD \sqrt{F(GHz)} dB Maxi$ 

RF leakage - ( AD - F(GHz)) dB Maxi

Voltage rating 250 Veff Maxi

Dielectric withstanding voltage Insulation resistance 500 Veff mini 1000 M $\Omega$  mini

#### **ENVIRONMENTAL**

Operating temperature -55/+155 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

#### **OTHERS CHARACTERISTICS**

Assembly instruction

Others:

#### MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0.390** g

Issue: 0422 A

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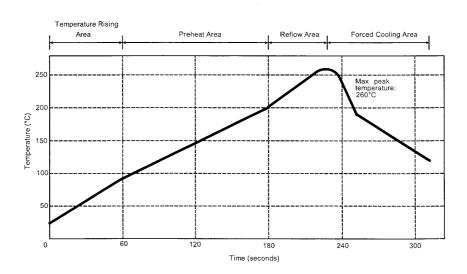
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#### **SOLDER PROCEDURE**

- 1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
  - We advise a thickness of 150 microns (0.006 inch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
   Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

#### TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

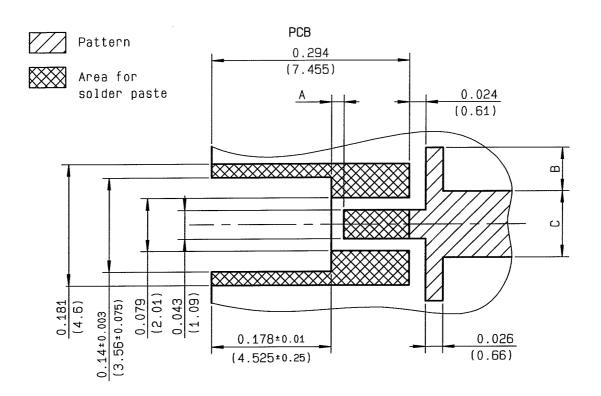
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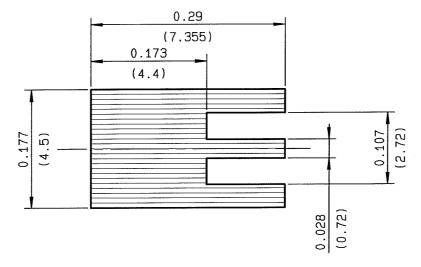
## R110.422.100

Series: MMCX



PCB THICKNESS	A	В	C
0.031 (0.79)	0.039 (0.99)	-	0.055 (1.4)
0.039 (0.99)	0.035 (0.89)	0.012 (0.3)	0.071 (1.8)
0.063 (1.6)	0.016 (0.41)	0.063 (1.6)	0.11 (2.79)

# SHADOW OF MMCX RECEPTACLE FOR VIDEO CAMERA



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